

■ **Features**

- 0.2 inch single color display
- Long lifetime operation
- IC compatible
- Low power dissipation
- Black surface with white segment
- Number of pin: 10

■ **Applications**






- Indicating device
- Overflow indication

■ **Absolute Maximum Rating** (Ta=25°C)

Item	Symbol	Value		Unit
		YG/Y/R	B/G	
DC Forward Current	I _F	25	25	mA
Pulse Forward Current#	I _{FP}	100	100	mA
Reverse Voltage	V _R	5	5	V
Power Dissipation	P _t	62.5	72	mW
Operating Temperature	Topr	-30 ~ +70		°C
Storage Temperature	Tstg	-40~ +85		°C
Lead Soldering Temperature(1.6mm from seating plane)	Tsol	260°C/5sec		°C

#Pulse width Max.10ms Duty ratio max 1/10

■ **Electrical -Optical Characteristics** (Ta=25°C)

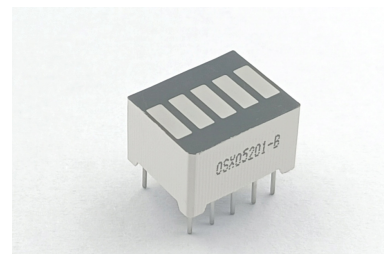
Part Number	Color			V _F (V)*			I _R (μA)	I _v (mcd)*			λD(nm)*		
				Min.	Typ.	Max.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.
				I _F =20mA			V _R =5V			I _F =20mA			
OSX05201-B	Blue	B		-	3.1	3.6	20	-	50	-	-	465	-
OSX05201-G	Pure Green	G		-	3.1	3.6	20	-	200	-	-	525	-
OSX05201-YG	Yellow Green	YG		-	2.1	2.5	20	-	35	-	-	570	-
OSX05201-Y	Yellow	Y		-	2.1	2.5	20	-	35	-	-	590	-
OSX05201-R	Red	R		-	2.1	2.5	20	-	35	-	-	630	-

*1 Tolerance of measurements of dominant wavelength is +1nm

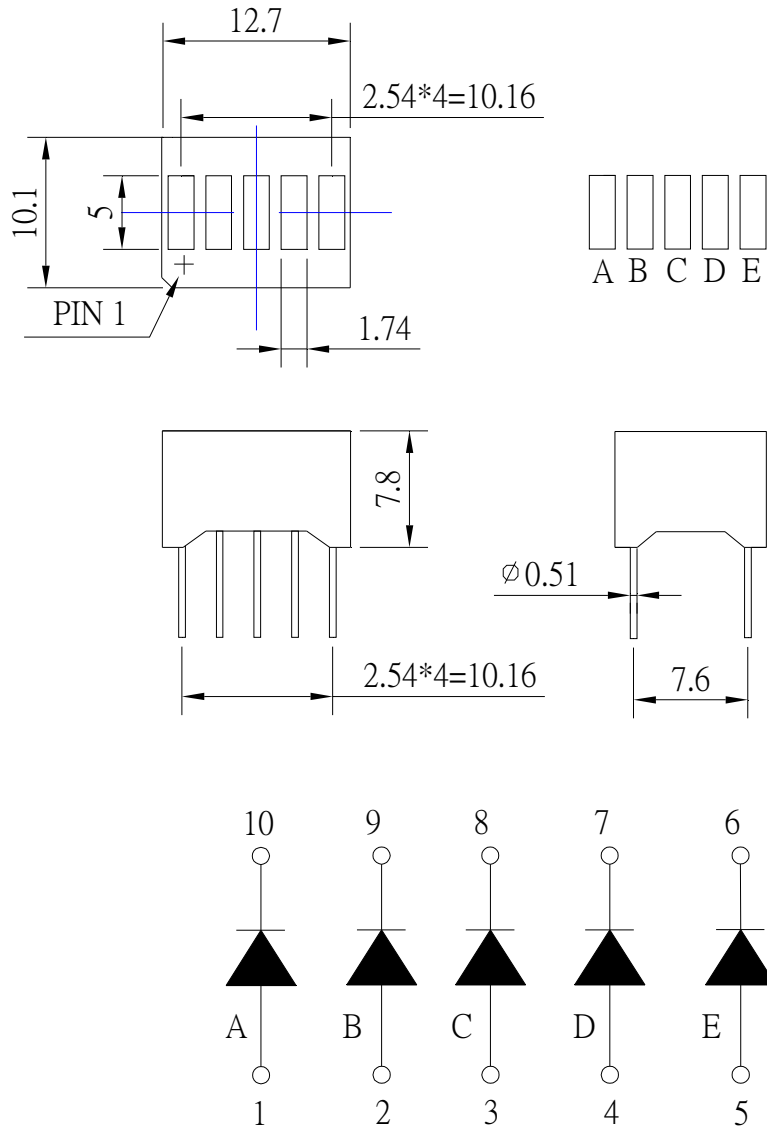
*2 Tolerance of measurements of luminous intensity is +15%

*3 Tolerance of measurements of forward voltage is±0.1V

■ **Photo**



■ Package Dimensions and Pin Function



Note:

1, Unit : mm (Tolerance: ± 0.25 mm unless otherwise noted)

2, The slope angle of any PIN may be $\pm 5.0^\circ$ Max

LAMP APPLICATION (PB FREE SOLDERJING)

Apply to Display (DIP) SERIES.

Description:

(1) Manual soldering (Solder Iron)

- (1.1) Temperature at tip of the iron: 350°C Max.
- (1.2) It's banned to load any stress on the resin during soldering.
- (1.3) Soldering time: 3sec.Max.(one time only.)
- (1.4) Leave 3mm of minimum distance from the base of the epoxy.

(2) Dip Soldering (Wave Soldering-Solder Bath)

- (2.1) Leave 3mm of minimum distance from the base of the epoxy.
Soldering beyond the base of the tie bar (stand off) is recommended.
- (2.2) When soldering, do not put stress on the Display during heating.
- (2.3) Cutting the lead frames at high temperatures may cause LED failure.
- (2.4) Never take next process until the component is cooled down to room temperature after reflow.
- (2.5) After soldering, do not warp the circuit board.
- (2.6) The recommended dip soldering profile is the following.

